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 Members of the Texas Instruments Widebus[™] Family 	SN54LVTH16373 WD PACKAGE SN74LVTH16373 DGG OR DL PACKAGE (TOP VIEW)
 State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation 	1 OE 1 48 1LE 1 Q1 2 47 1D1 1 Q2 3 46 1D2
 Support Mixed-Mode Signal Operation	GND [4 45] GND
(5-V Input and Output Voltages With	1Q3 [5 44] 1D3
3.3-V V _{CC})	1Q4 [6 43] 1D4
 Support Unregulated Battery Operation	V _{CC} [] 7 42 [] V _{CC}
Down to 2.7 V	1Q5 [] 8 41 [] 1D5
 Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	1Q6 9 40 106 GND 10 39 GND
 I_{off} and Power-Up 3-State Support Hot	1Q7 11 38 1D7
Insertion	1Q8 12 37 1D8
 Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors 	2Q1 [13 36] 2D1 2Q2 [14 35] 2D2 GND [15 34] GND 2Q3 [16 33] 2D3
 Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise 	$2Q3 [16 33] 2D3 2Q4 [17 32] 2D4 V_{CC} [18 31] V_{CC}$
 Flow-Through Architecture Optimizes PCB	2Q5 [19 30] 2D5
Layout	2Q6 [20 29] 2D6
 Latch-Up Performance Exceeds 500 mA Per	GND [21 28] GND
JESD 17	2Q7 [22 27] 2D7
 ESD Protection Exceeds 2000 V Per	2 <u>Q8</u> 23 26 2208
MIL-STD-883, Method 3015; Exceeds 200 V	2OE 24 25 2LE

MIL-STD-883, Method 3015; Exceeds 200 Using Machine Model (C = 200 pF, R = 0)

 Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'LVTH16373 devices are 16-bit transparent D-type latches with 3-state outputs designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.



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SN54LVTH16373, SN74LVTH16373 3.3-V ABT 16-BIT TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS SCBS144K – MAY 1992 – REVISED APRIL 1999

description (continued)

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16373 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVTH16373 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE (each 8-bit section)										
INPUTS OUTPUT										
OE	LE	Q								
L	Н	Н	Н							
L	Н	L	L							
L	L	Х	Q ₀							
н	Х	Х	Z							



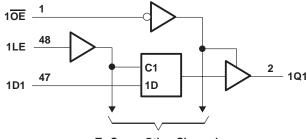
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logic symbol[†]

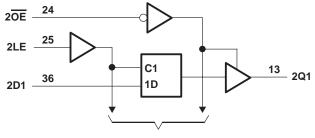
1 <mark>0</mark> E	1	1EN			
1LE	48	C3			
2 <mark>0E</mark>	24	2EN			
	25				
2LE		C4			
1D1	47	3D	1 🗸	2	1Q1
1D2	46			3	1Q2
1D3	44		_	5	1Q3
1D3	43			6	1Q4
1D5	41		_	8	1Q5
1D6	40			9	1Q6
1D7	38		_	11	1Q7
1D8	37		_	12	1Q8
2D1	36	4D	2 ▽	13	2Q1
2D1	35	40	2 V	14	2Q2
2D2	33		_	16	2Q2
2D3 2D4	32		_	17	2Q3
2D4 2D5	30		_	19	2Q4
2D5 2D6	29		_	20	2Q5
2D6 2D7	27		_	22	2Q0 2Q7
2D7 2D8	26			23	
200					2Q8

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels







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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Voltage range applied to any output in the high-impedance or power-off state, V _O (see Note 1)
Voltage range applied to any output in the high state, V _O (see Note 1) -0.5 V to V _{CC} + 0.5 V Current into any output in the low state, I _O : SN54LVTH16373 96 mA SN74LVTH16373 128 mA Current into any output in the high state, I _O (see Note 2): SN54LVTH16373 48 mA SN74LVTH16373 64 mA
Current into any output in the low state, I _O : SN54LVTH16373 96 mA SN74LVTH16373 128 mA Current into any output in the high state, I _O (see Note 2): SN54LVTH16373 48 mA SN74LVTH16373 64 mA
SN74LVTH16373 128 mA Current into any output in the high state, I _O (see Note 2): SN54LVTH16373 48 mA SN74LVTH16373 64 mA
SN74LVTH16373 128 mA Current into any output in the high state, I _O (see Note 2): SN54LVTH16373 48 mA SN74LVTH16373 64 mA
Current into any output in the high state, I _O (see Note 2): SN54LVTH16373
Input clamp current, I _{IK} (V _I < 0)
Output clamp current, I_{OK} ($V_O < 0$)
Package thermal impedance, θ _{JA} (see Note 3): DGG package
DL package
Storage temperature range, T _{stg}

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			SN54LVTI	H16373	SN74LVTI	UNIT	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	ly voltage				3.6	V
VIH	High-level input voltage	2		2		V	
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		5.5		5.5	V	
ЮН	High-level output current		-24		-32	mA	
IOL	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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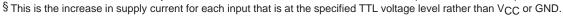
electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			4LVTH16	373	SN74					
VIK		TEST CONDITIONS			TYP†	MAX	MIN	TYP [†]	MAX	UNIT		
		V _{CC} = 2.7 V,	lj = -18 mA			-1.2			-1.2	V		
		V _{CC} = 2.7 V to 3.6 V,	I _{OH} = -100 μA V _{CC} -0.2 V				V _{CC} –0	.2				
M =		V _{CC} = 2.7 V,	IOH =8 mA	2.4			2.4			V		
VOH			I _{OH} = -24 mA	2						v		
		$V_{CC} = 3 V$	I _{OH} = -32 mA				2					
			I _{OL} = 100 μA			0.2			0.2			
		$V_{CC} = 2.7 V$	I _{OL} = 24 mA			0.5			0.5			
\/			I _{OL} = 16 mA			0.4			0.4	v		
VOL			I _{OL} = 32 mA			0.5			0.5	V		
		$V_{CC} = 3 V$	I _{OL} = 48 mA			0.55						
			I _{OL} = 64 mA						0.55			
		V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			10			10			
4	Control inputs	V _{CC} = 3.6 V,	$V_{I} = V_{CC} \text{ or } GND$			±1			±1			
	Doto inputo	V _{CC} = 3.6 V	Al = ACC			1			1	μA		
Data inputs		VCC = 3.0 V	V _I = 0			-5			-5			
loff		$V_{CC} = 0,$	V_{I} or V_{O} = 0 to 4.5 V						±100	μΑ		
-	Data inputs	V _{CC} = 3 V	V _I = 0.8 V	75			75					
ha us			V _I = 2 V	-75			-75					
l(hold)		V _{CC} = 3.6 V [‡] ,	VI = 0 to 3.6 V						500 -750	μA		
IOZH	-	V _{CC} = 3.6 V,	V _O = 3 V			5			5	μA		
IOZL		V _{CC} = 3.6 V,	V _O = 0.5 V			-5			-5	μA		
IOZPU		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, V _O = OE = don't care	= 0.5 V to 3 V,			±100*			±100	μA		
IOZPD		$\frac{V_{CC}}{OE} = 1.5 \text{ V to 0, } V_{O} = 0.5 \text{ V to 3 V,}$ OE = don't care				±100*			±100	μΑ		
lcc		V _{CC} = 3.6 V,	Outputs high			0.19			0.19			
		$I_{O} = 0,$	Outputs low	5		5			mA			
		$V_{I} = V_{CC} \text{ or } GND$	Outputs disabled		0.19		0.19			1		
∆I _{CC} §		$V_{CC} = 3 \text{ V}$ to 3.6 V, One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at V_{CC} or GND				0.2			0.2	mA		
Ci		VI = 3 V or 0			3			3		pF		
Co		V _O = 3 V or 0			9			9		pF		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.





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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				SN54LVTH16373				SN74LVTH16373			
			3.3 V 3 V	V _{CC} =	2.7 V	= ۷ _{CC} ± 0.3	3.3 V 3 V	V _{CC} =	2.7 V	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
tw	Pulse duration, LE high	3		3		3		3		ns	
t _{su}	Setup time, data before LE \downarrow	2		2		1		0.6		ns	
t _h	Hold time, data after LE \downarrow	3		3.3		1		1.1		ns	

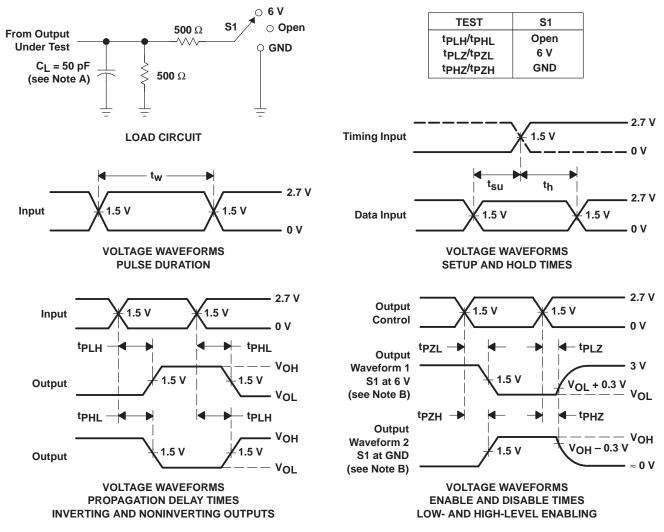
switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

		SN54LVTH16373										
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX	
^t PLH	D	Q	1.4	4.5		5.2	1.5	2.7	3.8		4.2	ns
^t PHL	D	ý	1.4	4.4		4.8	1.5	2.5	3.6		4	115
^t PLH	LE	Q	1.8	5.5		5.8	2.1	3	4.3		4.8	ns
^t PHL		ý	1.8	5.2		5.6	2.1	2.9	4		4	115
^t PZH	OE	Q	1.4	5.7		6.7	1.5	2.8	4.3		5.1	ns
tPZL		ý	1.4	5.5		6	1.5	2.8	4.3		4.7	115
^t PHZ	OE	Q	2	6		6.2	2.4	3.5	5		5.4	
^t PLZ	UE	ý	1.4	5.2		5.6	2	3.2	4.7		4.8	ns
^t sk(o)									0.5			ns

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \le 10 MHz, Z_O = 50 Ω , t_f \le 2.5 ns. t_f \le 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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